

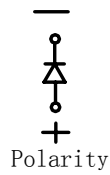
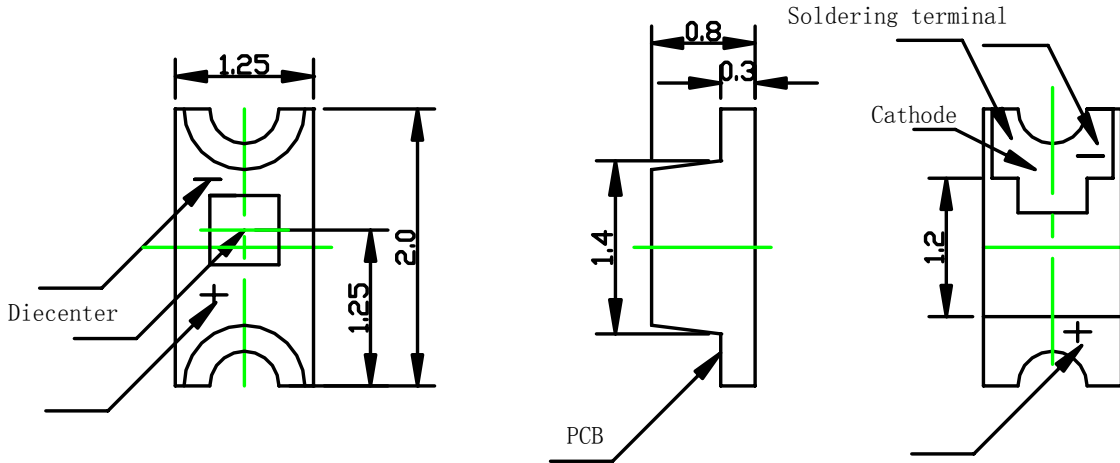
SHEN ZHEN XUAN CAI ELECTRONIC CO.,LTD

■ Features

1. Mono-color type.
2. Dimensions: 2.0(L)x1.25(W)x0.8(H)mm, being ultra-small size.
3. Compatible with automatic placement equipment.
4. Compatible with infrared and vapor phase reflow solder process.

Resin

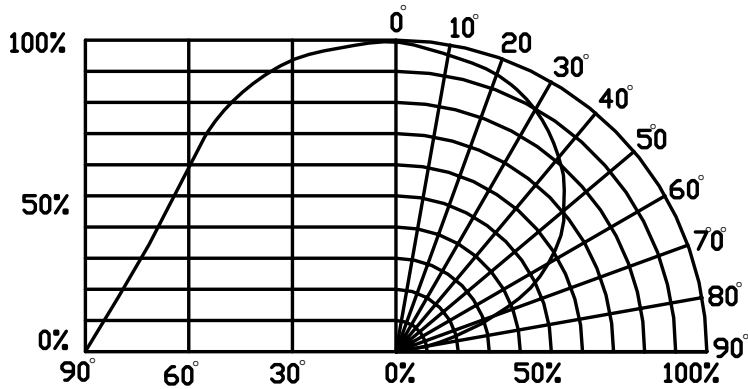
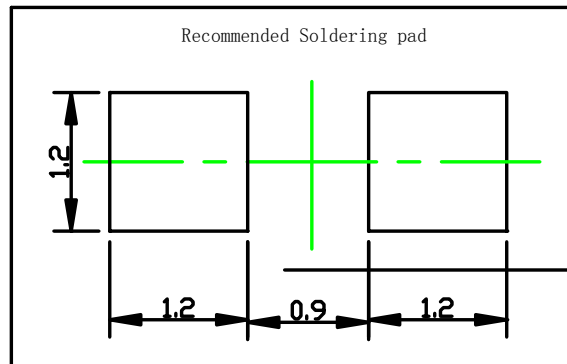
■ Dimensions



Notes:

1. Tolerance ± 0.1
2. Unit: mm

■ Far Field Pattern



Relative Luminous Intensity vs. Radiation Angle

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■ Descriptions

PART NO	Chip		Lens Color
	Material	Emitted Color	
XC-0805YVC	AlGaInP	Yellow	WATER CLEAR

■ Absolute Maximum Ratings (Ta = 25°C)

Items	Symbol	Absolute maximum Rating	Unit
Forward Current(DC)	I _F	50	mA
Peak Forward Current*	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Operation Temperature	T _{opr}	-40 ~ +95	°C
Storage Temperature	T _{stg}	-40 ~ +100	°C
Lead Soldering Temperature	T _{sol}	Max.260°C for 5 sec Max. (3mm from the base of the epoxy bulb)	

*Pulse width ≦ 0.1msec duty ≦ 1/10

■ Typical Electrical & Optical Characteristics (Ta = 25°C)

Items	Symbol	Condition	Min.	Typ.	Max.	Unit
Power Dissipation	PD	IF = 20mA	---	40	---	mW
Forward Voltage	VF	IF = 20mA	1.7	---	2.4	V
Reverse Current	IR	VR = 5V	---	---	5	μA
Dominant Wavelength	λD	IF = 20mA	580	---	595	nm
Luminous Intensity	IV	IF = 20mA	---	100	---	mcd
50% Power Angle	2θ½	IF = 20mA	---	120	---	Deg

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■ Typical Electrical/Optical Characteristics Curves ($T_a=25^\circ$ Unless Otherwise Noted)

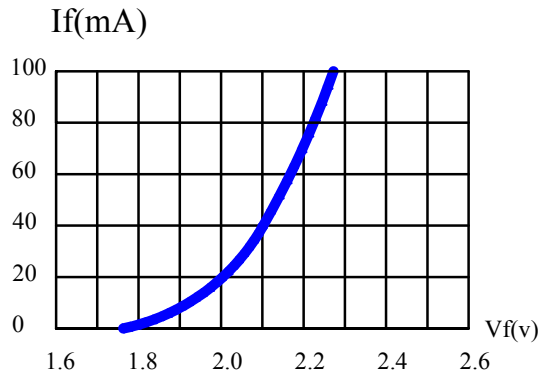


Fig. 1 Forward Current vs Forward Voltage

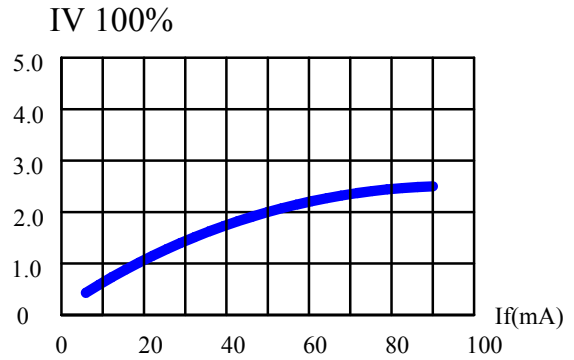


Fig. 2 Relative Luminous Intensity vs Forward Voltage

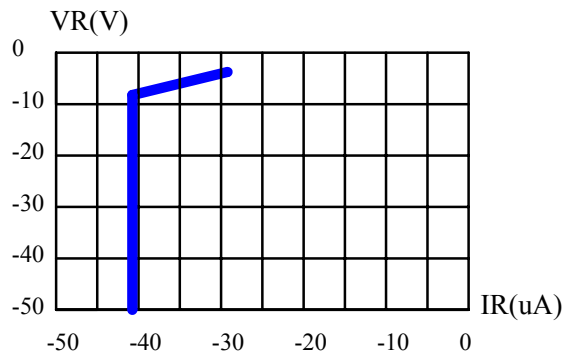


Fig. 3 Reverse Current vs Reverse Voltage

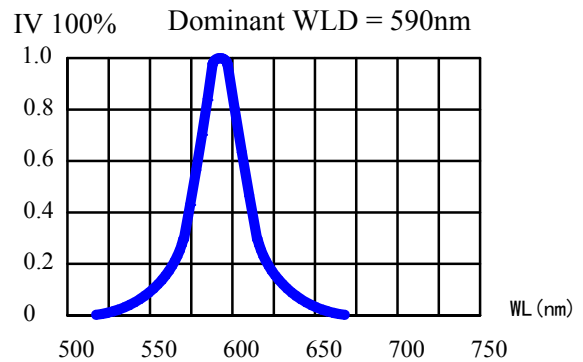


Fig. 4 Relative Luminous Intensity vs Wavelength

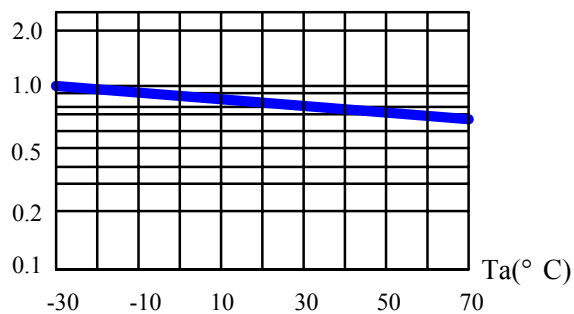


Fig. 5 Relative Luminous Intensity vs Ambient Temperature

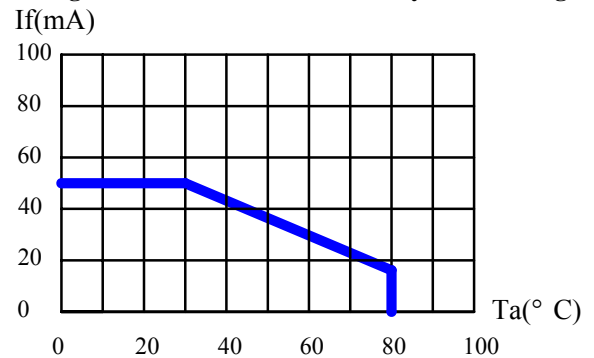


Fig. 6 Maximum Forward Current vs Ambient Temperature